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(54) Title: A HIGH-PERFORMANCE NON-CONDUCTIVE POLYMER MATERIAL FOR ELIMINATION OF ELECTROSTATIC CHARGE AT SOURCE

(57) Abstract: The present invention relates to a non-conductive polymer material for applying a non-conductive coat to a surface. The non-conductive polymer material comprises a first polymer selected from the group consisting of polyvinyl acetate and polyethylene oxide; a second polymer being polyvinylidene fluoride; and a solvent selected from the group consisting of dimethyl sulfoxide, tetrahydrofuran, toluene and dimethylformamide. The present invention also relates to a method of eliminating electrostatic charge on a surface by applying the non-conductive polymer material of the present invention to at least one surface of an object to form a non-conductive coat on the surface.

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